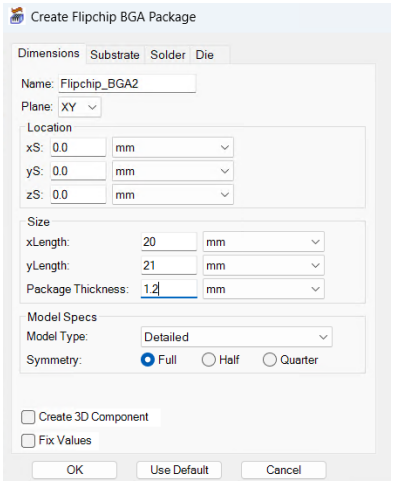
Lab 2 Q3D **Package Cross-Section Modeling**

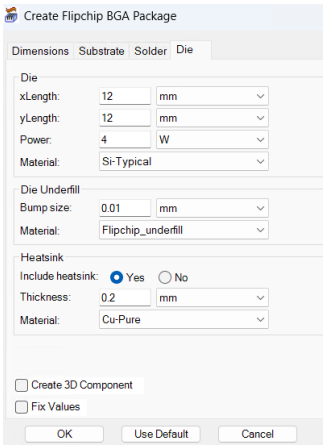
Tool used: Ansys Elctronic Desktop (AEDT) 2022 R2

File name: flipchip_bga.aedt

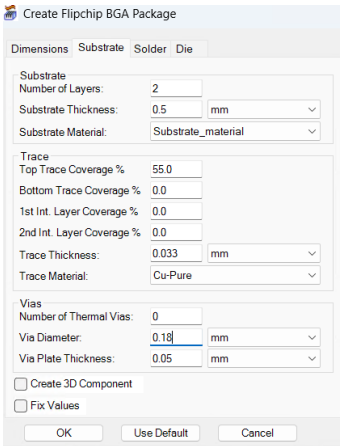
Package Dimensions: 20x20x1.6mm



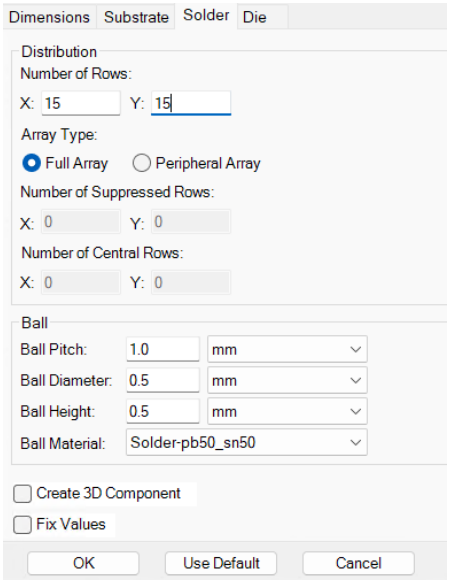
Die Dimensions: 12x12mm, Power: 4mm, include heatsink

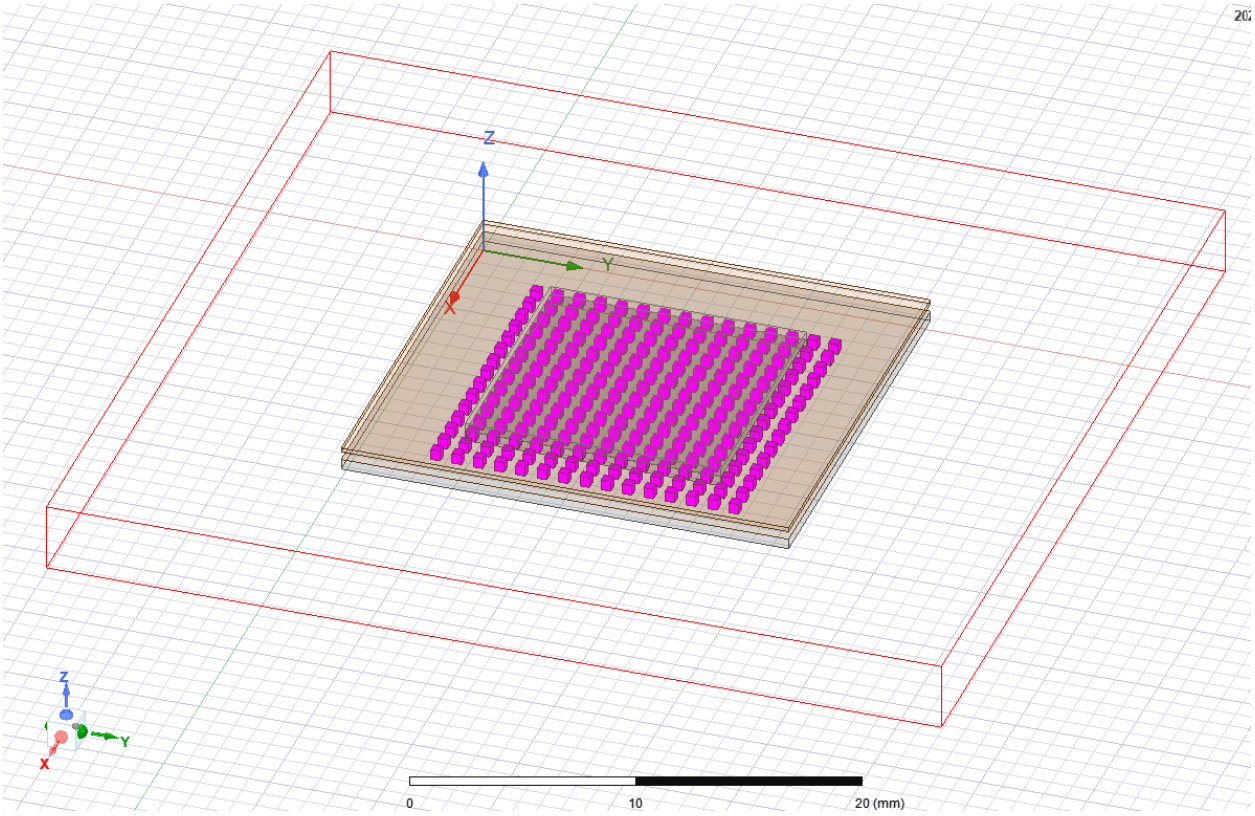


Substrate:



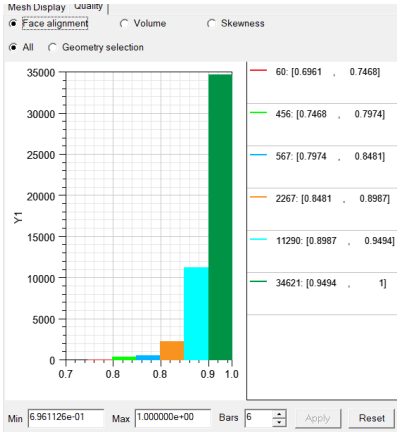
Solder: 15x15 rows



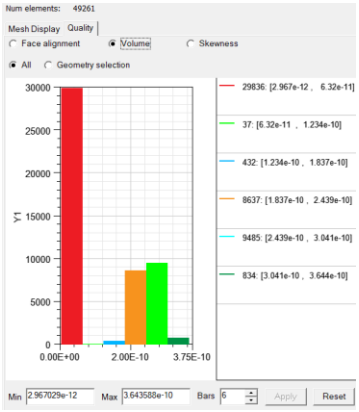


Mesh Quality

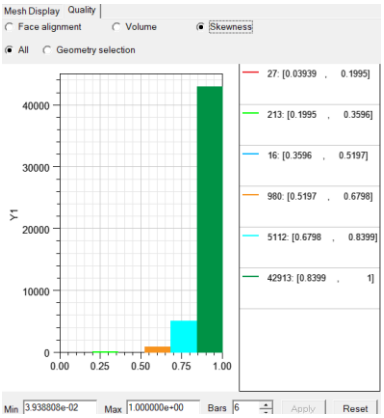
Face alignment



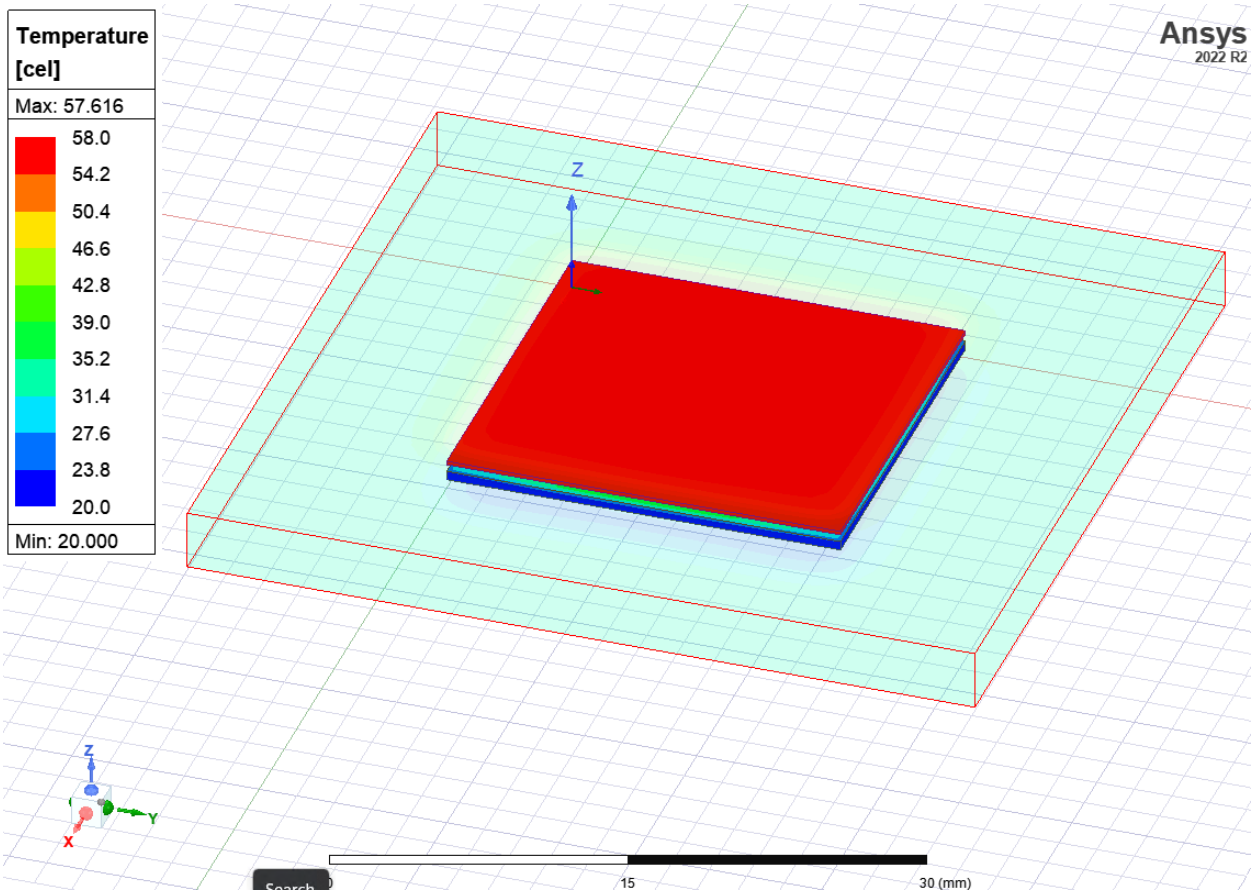
Volume

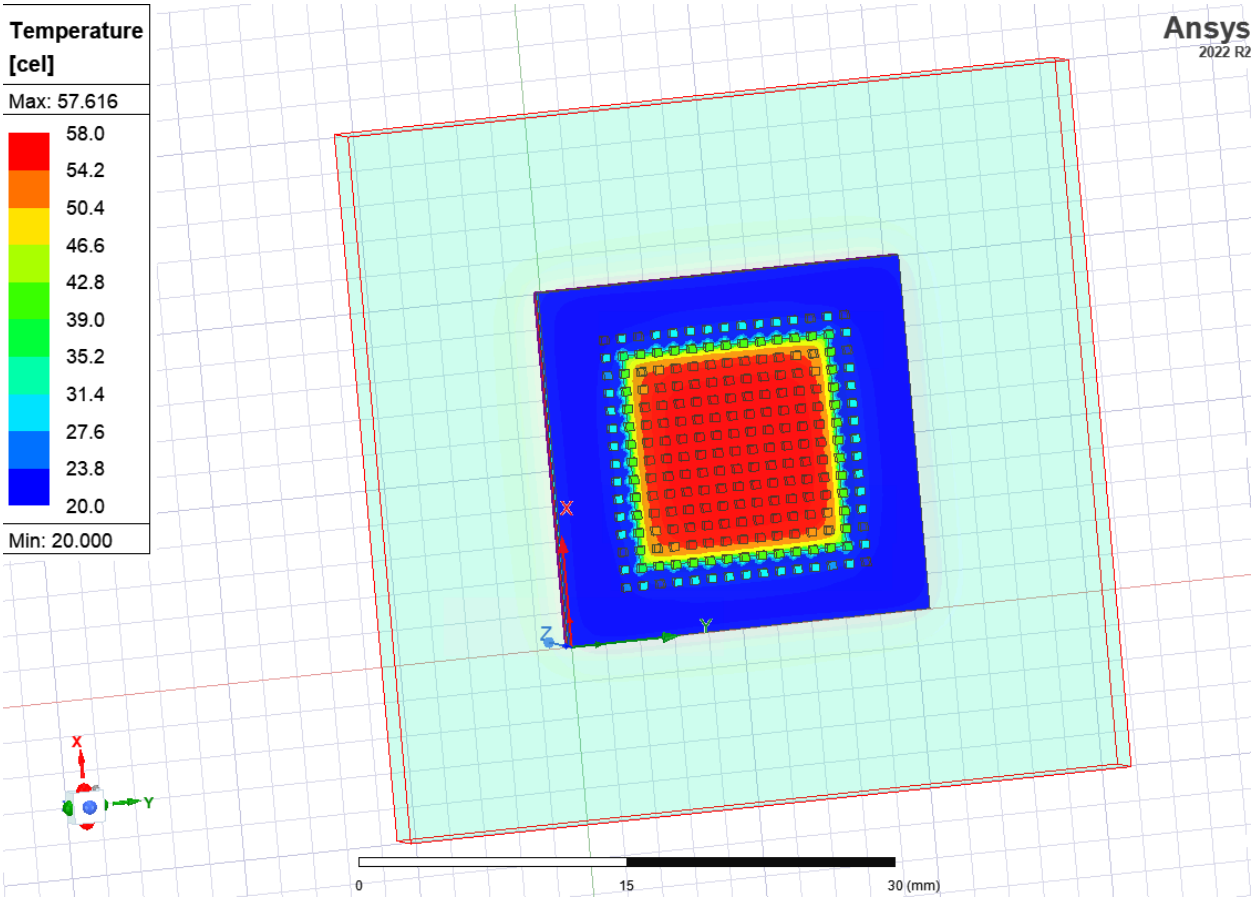


Skewness



Final results: heatsink was used in design so it brought down the temperature at die (junction)




Temperature [cel]
Max: 57.616
58.0
54.2
50.4
46.6
42.8
39.0
35.2
31.4
27.6
23.8
20.0
Min: 20.000
Ansys
2022 R2
X
Y
Z
0
15
30 (mm)